

鉛 (Lead):

◎Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
(2002/95/EC)

鉛使用於陰極射線管 (CRT) 玻璃、電子組件及螢光管。

◎ Lead as an alloying element in steel containing up to 0.35 % lead by weight, aluminum containing up to 0.4 % lead by weight and as a copper alloy containing up to 4 % lead by weight (2002/95/EC)

使用於鋼材中的鉛含量最高為 0.35 % (重量)，鋁材中含鉛量最高為 0.4 % (重量)，銅合金中含鉛量最高為 4 % (重量)。

◎Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead (2005/747/EC)

鉛使用於高溶解溫度的焊料 (鉛含量超過 85% 之鉛基礎合金)。

◎ lead in solders for servers, storage, and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for ?telecommunication) (2005/747/EC)

使用於伺服器、記憶體、儲存系統、網路基礎建設配備如開關、信號、傳播及電子通訊的網路管理中焊料的鉛。

◎ lead in electronic ceramic ./parts/ (e.g. piezoelectronic devices) (2005/747/EC)

鉛使用於電子器材中陶制零件，如壓電器

◎lead-bronze bearing shells and bushes(2005/717/EC)

用於鉛青銅軸承外殼。

◎Lead and cadmium in optical and filter glass.(2005/747/EC)

鉛和鎘使用於光學玻璃和護目鏡(濾光玻璃)

◎Lead as a coating material for the thermal conduction module c-ring(2005/747/EC)

鉛作為傳熱性模件(熱導槍釘模組) c-ring 的塗料。

◎ Lead in solders consisting of more than two elements for the connection between the pins and? the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight(2005/747/EC)

含兩種成份以上金屬的焊劑-用於連接微處理器的 pins 和封裝，而該含鉛量超過 80% ~85%

◎ Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages(2005/747/EC)

用於焊接半導體終端和集成電路板載體的焊料中含鉛量。

◎Lead in linear incandescent lamps with silicate coated tubes (2006/310/EC)

管狀白熾燈硅酸鹽塗層燈管中的鉛。

◎ Lead halide as radiant agent in High Intensity Discharge (HID) lamps used for professional reprography applications (2006/310/EC)

專業復印設備用的高強度放電燈中作為發光劑的鹵化鉛。

◎ Lead as activator in the fluorescent powder (1 % lead by weight or less) of discharge lamps? when used as sun tanning lamps containing phosphors such as BSP (BaSi2O5:Pb) as well as? when used as speciality lamps for diazo-printing reprography, lithography, insect traps,? photochemical and curing processes containing phosphors such as SMS ((Sr,Ba)2MgSi2O7:Pb) (2006/310/EC)

當放電燈被用作含磷仿日晒燈（例如 BSP）、或二氮化合物列印、平版印刷、捕虫器，以及含磷化學和含磷食物加工過程的專業燈時（例如 SMS），放電燈中的螢光粉觸媒劑的鉛

（鉛含量 1%以下）。

鉛 (Lead):

◎Lead with PbBiSn-Hg and PbInSn-Hg in specific compositions as main amalgam and with PbSn-Hg as auxiliary amalgam in very compact Energy Saving Lamps (ESL) (2006/310/EC)

緊縮節能燈中作為汞的特定成分中 PbBiSn-Hg 及 PbInSn-Hg 中的鉛以及作為輔助汞合金中 PbSn-Hg 中的鉛。

◎Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for? Liquid Crystal Displays (LCD)) (2006/310/EC)

液晶顯示器中焊接前後平版螢光燈基質的玻璃中的氧化鉛

◎Lead in printing inks for the application of enamels on borosilicate glass.(2006/691/EC)

用於硼矽玻璃瓷漆印墨中的鉛

◎Lead as impurity in RIG(rare earth iron garnet)Faraday rotators used for fibre optic communications systems.(2006/691/EC)

用於光纖通訊系統以稀土鐵石榴石晶體制成的法拉第旋轉器中作為雜質的鉛

◎Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with NiFe lead frames and lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm or less with copper lead frames. .(2006/691/EC)

小螺距零件表面材質所含的鉛

◎Lead in solders for the soldering to machined through hole discoidal and planar array ceramic multilayer capacitors. (2006/691/EC)

通孔盤狀及平面陣列陶瓷多層電容器焊料所含的鉛

◎Lead oxide in plasma display panels (PDP) and surface conduction electron emitter displays (SED) used in structural elements; notably in the front and rear glass dielectric layer, the bus electrode, the black stripe, the address electrode, the barrier ribs, the seal frit and frit ring as well as in print pastes. (2006/691/EC)

等離子顯示屏及表面傳導式電子發射顯示器的構件所用的氧化鉛

◎ Lead oxide in the glass envelope of Black Light Blue (BLB) lamps. (2006/691/EC)

藍黑燈管玻璃外罩所含的氧化鉛

◎ Lead alloys as solder for transducers used in high-powered (designated to operate for several hours at acoustic power levels of 125 dB SPL and above) loudspeakers.’ (2006/691/EC)

在大功率揚聲器中作為轉換器焊料的鉛合金

鎘(Cadmium) :

◎ Cadmium plating except for applications banned under Directive 91 / 338 / EC amending Directive 76 / 769 / EC relating to restrictions on the marketing and use of certain dangerous substances and preparations 。 (2005/747/EC)

電接點的鎘及其化合物、鍍鎘，但依據第 91/338/EC 號指令修正第 76/769/EC 號指令有關限制行銷及禁止使用某些危險物質及成分之規定禁止者，不在此限。

◎ Lead and cadmium in optical and filter glass. (2005/747/EC)

鉛和鎘使用於光學玻璃和護目鏡(濾光玻璃)

◎ Cadmium in printing inks for the application of enamels on borosilicate glass.(2006/691/EC)

用於硼矽玻璃瓷漆印墨中的鉛

六價鉻(Hexavalent - Chromium) :

◎ Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators

電冰箱中作為碳鋼冷卻系統防腐劑的六價鉻。(2002/95/EC)

◎ Hexavalent chromium in corrosion preventive coatings of unpainted metal sheetings and fasteners used for corrosion protection and Electromagnetic Interference Shielding in equipment falling under category three of Directive 2002/96/EC (IT and telecommunications equipment).Exemption granted until 1 July 2007.’

用於防止腐蝕及預防 WEEE 指令第三類設備(資訊與電信設備)電磁干擾的未著色金屬片

及鈕扣的防腐塗層所含的六價鉻

汞(Mercury) :

◎Mercury in compact fluorescent lamps not exceeding 5 mg per lamp(2002/95/EC)

小型日光燈泡其重金屬汞含量不得超過 5mg /每支燈泡

◎ Mercury in straight fluorescent lamps for general purposes not exceeding:

halophosphate 10 mg

triphosphate? with normal lifetime 5 mg

triphosphate? with long lifetime 8 mg. (2005/95/EC)

直式 (straight) 日光燈泡的含汞種類及重量，如下：

含鹵素磷酸鹽 (halo phosphate) 量不得超過 10mg /每支燈泡

普通壽命的燈泡型，其含三基磷酸鹽 (triphosphate?) 量不得超過 5mg /每支燈泡

延長壽命的燈泡型，其含三基磷酸鹽 (triphosphate?) 量不得超過 8mg /每支燈泡。

◎Mercury in straight fluorescent lamps for special purposes. (2002/95/EC)

汞使用於特殊用途之直式日光燈管。

◎ Mercury in other lamps not specifically mentioned in this Annex (2002/95/EC)

附件中未特別提及用於其他照明燈具的含汞量

十溴聯苯醚 (Deca BDE) :

應用於高分子類 (Polymeric) 之十溴聯 醚之含量(2005/717/EC)